

Product Specification

100G QSFP28 to 4 x 25G SFP28 Passive Direct Attach Copper Breakout Cable

PN: Q100-4S25-C



Features

- Supporting 100Gbps to 4x25Gbps
- Wire AWG:30AWG,28AWG,26AWG
- Available length range 1m~5m
- Data rates per channel 25.78Gbps
- Operating data rate 103.125Gbps
- Power supply: +3.3V
- Max power dissipation <0.1W
- Commercial temperature range 0°C to 70°C
- High-Density QSFP28 38-PIN and 4x SFP28 20-PIN Connector
- I2C based two-wire serial interface for EEPROM signature which can be customized

Compliance

- Compliant with SFP28 MSA and QSFP28 MSA
- Compliant with Electrical MSA SFF-8636 and SFF8431
- Compliant with Mechanical MSA SFF-8665 and SFF8432
- IEEE 802.3bj
- RoHS

Applications

- 100/25 Gigabit Ethernet
- Switches, servers,routers and HBA
- Data center cabling infrastructure
- High speed multi-channel parallel data connections

Description

The Q100-4S25-C is a high-performance, cost-effective solution designed for seamless interconnects between QSFP28 and SFP28 equipment. This hybrid passive copper cable assembly is ideal for short-reach, high-speed data transmission applications, offering a reliable and energy-efficient connectivity solution for data centers, HPC, and enterprise networks.

Compliant with SFF-8402 and SFF-8665 specifications, the QSFP28 to 4x SFP28 100G DAC breakout cable supports data rates of up to 25Gb/s per lane, delivering an aggregated bandwidth of 100Gb/s. This makes it an excellent choice for applications requiring high-density connectivity and efficient data transfer. The cable's breakout design allows a single QSFP28 port to connect to four SFP28 ports, providing flexibility and scalability in network configurations.

Product performance Specifications

1、 Basic Product Characteristics

Parameter	Symbol	Min	Typ.	Max	Unit
Storage Temperature	T _s	-40		85	°C
Operating Case Temperature	T _c	0		70	°C
Relative Humidity	RH	5		85	%
Power Supply Voltage	V _{cc}	3.135	3.3	3.475	V
Data Rate Per Lane	DR	1		25.78	Gbps

2、 High Speed Characteristics

Parameter	Symbol	Min	Typ.	Max	Unit	Conditions
Differential Impedance	RIN,P	90	100	110	Ω	
Insertion loss	SDD21	8		22.48	dB	12.8906GHz
Differential to common-mode return loss	SCD11	12		See1	Gbps	
	SCD22	10.58		See2		
Common-mode to common-mode output return loss	SCC11 SCC22	2			dB	0.2 to 19GHz
Differential Return Loss	SDD11	12.45		See3		0.05 to 4.1GHz
	SDD22	3.12		See4		4.1GHz to 19GHz
Differential to common Mode Conversion Loss	Scd21-1L	10		See5	dB	0.01 to12.89
						12.89 to15.7
		6.3				15.7 to19GHz
Channel Operating Margin	COM	3			dB	

Note1: Reflection Coefficient given by equation $SCD11(dB) < 22 - (20/25.78)f$, with f in GHz

Note2: Reflection Coefficient given by equation $SCD11(dB) < 15 - (6/25.78)f$, with finGHz

Note3: Reflection Coefficient given by equation $SDD11(dB) < 16.5 - 2 \times \text{SQRT}(f)$, with finGHz

Note4: Reflection Coefficient given by equation $SDD11(dB) < 10.66 - 14 \times \log_{10}(f/5.5)$, with finGHz

Note5: Reflection Coefficient given by equation $SCD21(dB) < 27 - (29/22)f$, with finGHz

3、 Product Optical and Electrical Characteristics

Test Type	Test Item	24AWG	26AWG	28AWG	30AWG
Electrical Characteristics	Differential impedance	100±5Ω at TDR	100±5Ω	100±5Ω	100±5Ω at TDR
	Mutual capacitance	14pF/ft nominal	14pF/ft nominal	14pF/ft nominal	14pF/ft nominal
	Time delay	1.31ns/ft nominal, (4.3ns/m) nominal	1.35ns/ft nominal	1.35ns/ft nominal	1.35ns/ft nominal, (4.3ns/m) nominal
	Time delay skew (within pairs)	80ps/10m maximum	120ps/8.5m maximum	120ps/7m maximum	50ps/5.5m maximum
	Time delay skew (between pairs)	350ps/10m maximum	500ps/8.5m maximum	500ps/7m maximum	350ps/5.5m maximum
	Attenuation	10dB/10m maximum at 1.25Ghz	10dB/8.5m maximum at 1.25Ghz	10dB/7m maximum at 1.25Ghz	8.4dB/5.5m maximum at 1.25Ghz
	Conductor DC Resistance	0.026Ω /ft maximum at 20°C	0.04Ω /ft maximum at 20°C	0.06Ω/ft maximum at 20°C	0.01Ω/ft maximum at 20°C
Physical Characteristics	Conductors (two pair)	24AWG Solid, Silver plated copper	26AWG Solid, Silver plated copper	28AWG Solid, Silver plated copper	30AWG Solid, Silver plated copper
	Insulation	Foam polyolefin	Foam polyolefin	Foam polyolefin	Foam polyolefin
	Pair drain wire	26AWG Solid, Silver plated copper	28AWG Solid, Silver plated copper	30AWG Solid, Silver plated copper	30AWG Solid, Silver plated copper
	Overall cable shield	Aluminum/polyester tape, 125% coverage, Tin plated copper braid, 38AWG, 85% coverage	Aluminum/polyester tape, 125% coverage, Tin plated copper braid, 38AWG, 85% coverage	Aluminum/polyester tape, 125% coverage, Tin plated copper braid, 38AWG, 85% coverage	Aluminum/polyester tape, 125% coverage, Tin plated copper braid, 38AWG, 85% coverage
	Outer diameter	6.0mm	5.2mm	4.7mm	4.2mm

QSFP Pin-out Definition

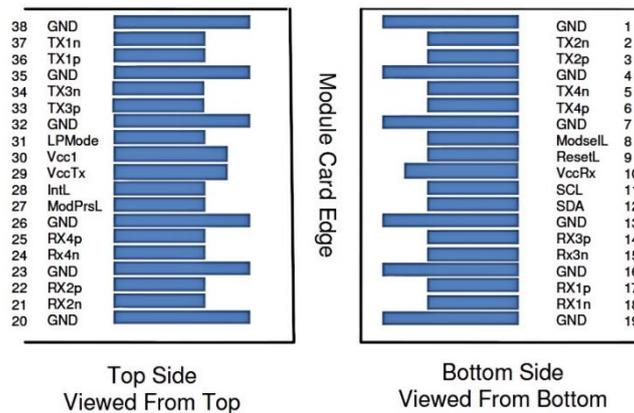


Figure3:QSFP Pin view

QSFP Pin Function Definitions

Pin	Logic	Symbol	Description	Note
1		GND	Ground	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input	3
4		GND	Ground	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input	3
7		GND	Ground	1
8	LVTTL-I	ModSelL	Module Select	4
9	LVTTL-I	ReSelL	Module Select	4
10		Vcc Rx	+3.3V Power Supply Receiver	2
11	LVC MOS-I/O	SCL	2-wire serial interface clock	4
12	LVC MOS-I/O	SDA	2-wire serial interface data	4
13		GND	Ground	1
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	3
15	CML-O	Rx3n	Receiver Inverted Data Output	3
16		GND	Ground	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	3
18	CML-O	Rx1n	Receiver Inverted Data Output	3
19		GND	Ground	1
20		GND	Ground	1
21	CML-O	Rx2n	Receiver Inverted Data Output	3
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	3
23		GND	Ground	1
24	CML-O	Rx4n	Receiver Inverted Data Output	3

25	CML-O	Rx4p	Receiver Non-Inverted Data Output	3
26		GND	Ground	1
27	LVTTL-O	ModPrsL	Module Present	4
28	LVTTL-O	IntL	Interrupt	4
29		Vcc Tx	+3.3V Power supply transmitter	2
30		Vcc1	+3.3V Power supply	2
31	LVTTL-I	LPMODE	Low Power Mode	4
32		GND	Ground	1
33	CML-I	Tx3p	Transmitter Non-Inverted Data Input	3
34	CML-I	Tx3n	Transmitter Inverted Data Input	3
35		GND	Ground	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	3
37	CML-I	Tx1n	Transmitter Inverted Data Input	3
38		GND	Ground	1

Note1:GND is the symbol for signal and supply (power) common for the QSFP+ module. All are common within the QSFP+ module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane.

Note2:Vcc Rx, Vcc1 and Vcc Tx are the receiver and transmitter power supplies and shall be applied concurrently. Requirements defined for the host side of the Host Edge Card Connector are listed in Table. Recommended host board power supply filtering is shown in Host board power supply circuit. Vcc Rx Vcc1 and Vcc Tx may be internally connected within the QSFP module in any combination. The connector pins are each rated for a maximum current of 500 mA.

Note3:High-speed signal interfaces require differential pairs (e.g. TX1+/TX1-) with tightly matched impedances (typically 100Ω).

Note4:The management and control signals are based on LVTTL level logic and are used for functions such as module selection and reset.

SFP Pin-out Definition

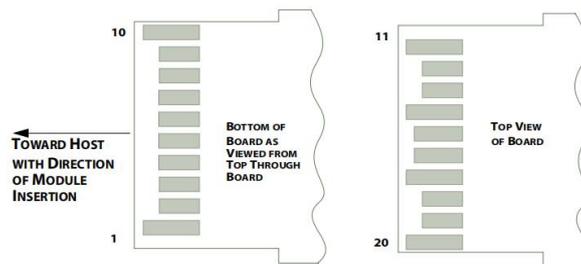


Figure4:SFP Pin view

SFP Pin Function Definitions

Pin	Logic	Symbol	Description	Note
1		VeeT	Module Transmitter Ground	1
2	LVTTL-O	TX_Fault	Module Transmitter Fault	2
3	LVTTL-I	TX_Disable	Transmitter Disable; Turns off transmitter laser output	3

4	LVTTTL-I/O	SDA	2-wire Serial Interface Data Line (Same as MOD-DEF2 as defined in the INF-8074i)	4
5	LVTTTL-I/O	SCL	2-wire Serial Interface Clock (Same as MOD-DEF1 as defined in the INF-8074i)	4
6		MOD_ABS	Module Absent, connected to VeeT or VeeR in the module	5
7	LVTTTL-I	RS0	Adaptive multi-rate operation	6
8	LVTTTL-O	RX_LOS	Receiver Loss of Signal Indication (In FC designated as RX_LOS, in SONET designated as LOS, and in Ethernet designated at Signal Detect)	2
9	LVTTTL-I	RS1	Adaptive multi-rate operation	6
10		VeeR	Module Receiver Ground	1
11		VeeR	Module Receiver Ground	1
12	CML-O	RD-	Receiver Inverted Data Output	
13	CML-O	RD+	Receiver Non-Inverted Data Output	
14		VeeR	Module Receiver Ground	1
15		VccR	Module Receiver 3.3 V Supply	
16		VccT	Module Transmitter 3.3 V Supply	
17		VeeT	Module Transmitter Ground	1
18	CML-I	TD+	Transmitter Non-Inverted Data Input	
19	CML-I	TD-	Transmitter Inverted Data Input	
20		VeeT	Module Transmitter Ground	1

Note1:The module signal ground pins, VeeR and VeeT, shall be isolated from the module case.

Note2:This pin is an open collector/drain output pin and shall be pulled up with 4.7kΩ-10kΩ to Host_Vcc on the host board. Pull ups can be connected to multiple power supplies, however the host board design shall ensure that no module pin has voltage exceeding module $V_{ccT/R} + 0.5V$.

Note3:This pin is an open collector/drain input pin and shall be pulled up with 4.7kΩ-10kΩ to VccT in the module.

Note4:See SFF-8431 4.2 2-wire Electrical Specifications.

Note5:This pin shall be pulled up with 4.7kΩ-10kΩ to Host_Vcc on the host board.

Note6:Connect with 30kΩ load pulled down to GND in the module.

QSFP Monitoring Specification

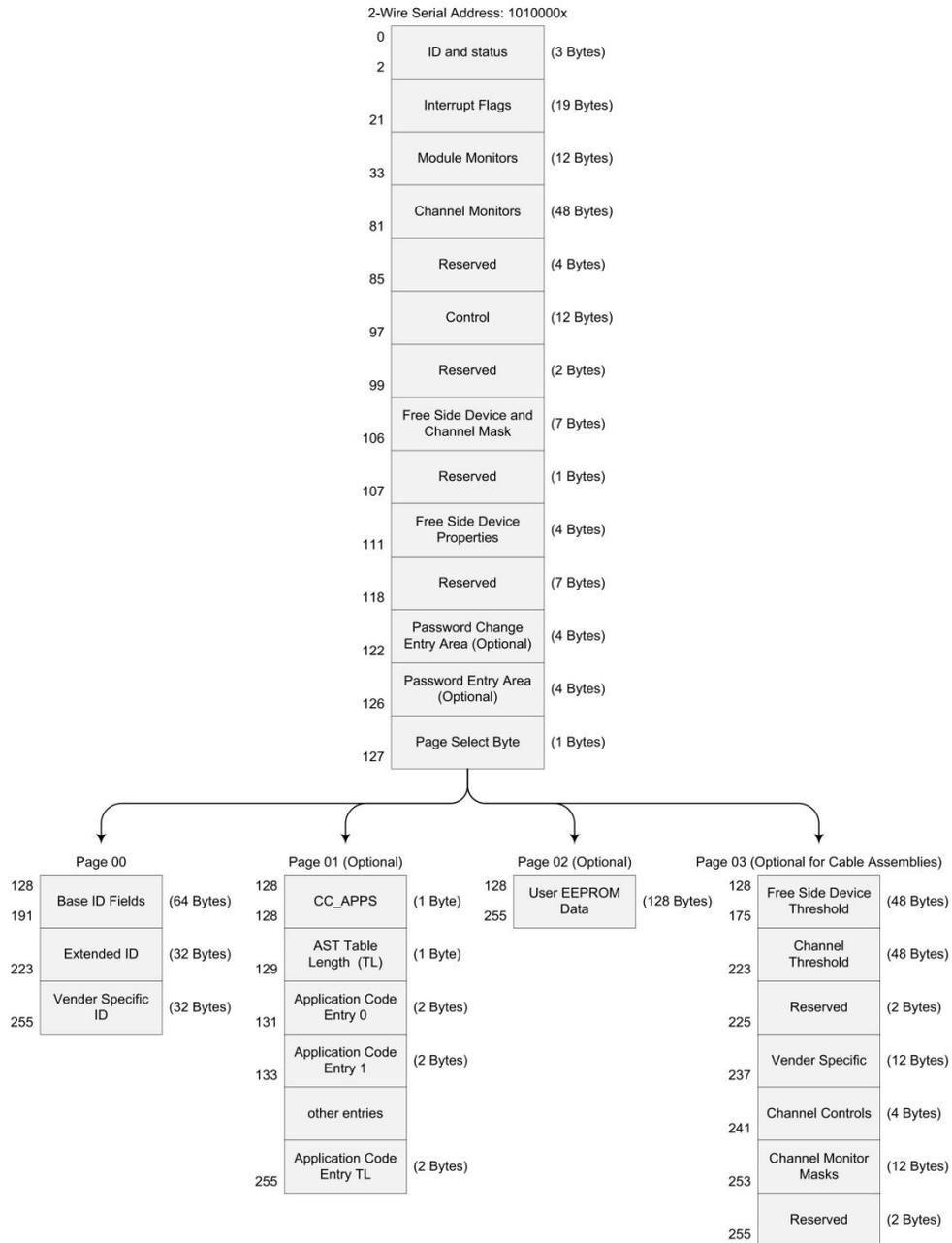


Figure5:QSFP Memory map

QSFP Memory map Table

Byte	Unit	Name	Description
Lower Page 00h			
0	1	Identifier	Type of transceiver, Page 00h Byte 0 and Page 00h Byte 128 shall contain the same parameter values.

1	1	Status	Revision Compliance
2	1	Status	Status indicators
3-21	19	Interrupt Flags	Consist of interrupt flags for LOS, Tx Fault, warnings and alarms. The non-asserted state shall be 0b.
22	1	Temperature MSB	Internally measured temperature (MSB)
23	1	Temperature LSB	Internally measured temperature (LSB)
24-25	2	Reserved	Reserved
26	1	Supply Voltage MSB	Internally measured supply voltage (MSB)
27	1	Supply Voltage LSB	Internally measured supply voltage (LSB)
28-29	2	Reserved	Reserved
30-33	4	Vendor Specific	Vendor Specific
34	1	Rx1 Power MSB	Internally measured Rx1 input power
35	1	Rx1 Power LSB	
36	1	Rx2 Power MSB	Internally measured Rx2 input power
37	1	Rx2 Power LSB	
38	1	Rx3 Power MSB	Internally measured Rx3 input power
39	1	Rx3 Power LSB	
40	1	Rx4 Power MSB	Internally measured Rx4 input power
41	1	Rx4 Power LSB	
42	1	Tx1 Bias MSB	Internally measured Tx1 bias
43	1	Tx1 Bias LSB	
44	1	Tx2 Bias MSB	Internally measured Tx2 bias
45	1	Tx2 Bias LSB	
46	1	Tx3 Bias MSB	Internally measured Tx3 bias
47	1	Tx3 Bias LSB	
48	1	Tx4 Bias MSB	Internally measured Tx4 bias
49	1	Tx4 Bias LSB	
50	1	Tx1 Power MSB	Internally measured Tx1 Power
51	1	Tx1 Power LSB	
52	1	Tx2 Power MSB	Internally measured Tx2 Power
53	1	Tx2 Power LSB	
54	1	Tx3 Power MSB	Internally measured Tx3 Power
55	1	Tx3 Power LSB	
56	1	Tx4 Power MSB	Internally measured Tx4 Power
57	1	Tx4 Power LSB	
58-65	8	Reserved	Reserved channel monitor set 4
66-73	8	Reserved	Reserved channel monitor set 5
74-81	8	Vendor Specific	Vendor Specific
82-85	4	Reserved	Reserved
86-99	14	Control	Control
100-106	7	Free Side Device and Channel Masks	Free Side Device and Channel Masks

107-110	4	Free Side Device Properties	Free Side Device Properties
111-112	2	Assigned for use by PCI Express	Used for:
			- The PCI Express External Cable Specification
			- The PCI Express OcuLink Specification
113-117	4	Free Side Device Properties	Free Side Device Properties
118	1	Reserved	Reserved
119-122	4	Password Change Entry Area	Password Change Entry Area
123-126	4	Password Entry Area	Password Entry Area
127	1	Page Select Byte	Page Select Byte
Upper Page 00h			
128	1	Identifier	Identifier Type of free side device.(See SFF-8024 Transceiver Management)
129	1	Ext. Identifier	Extended Identifier of free side device. Includes power classes, CLEI codes, CDR capability.
130	1	Connector Type	Code for media connector type. (See SFF-8024 Transceiver Management)
131-138	8	Specification Compliance	Code for electronic or optical compatibility.
139	1	Encoding	Code for serial encoding algorithm. (See SFF-8024 Transceiver Management)
140	1	Signaling rate, nominal	Nominal signaling rate, units of 100 MBd. For rate > 25.4 GBd, set this to FFh and use Byte 222.
141	1	Extended Rate Select Compliance	Tags for extended rate select compliance.
142	1	Length (SMF)	Link length supported at the signaling rate in byte 140 or page 00h byte 222, for SMF fiber in km *. A value of 1 shall be used for reaches from 0 to 1 km.
143	1	Length (OM3 50 um)	Link length supported at the signaling rate in byte 140 or page 00h byte 222, for EBW 50/125 um fiber (OM3), units of 2 m *
144	1	Length (OM2 50 um)	Link length supported at the signaling rate in byte 140 or page 00h byte 222, for 50/125 um fiber (OM2), units of 1 m *
145	1	Length (OM1 62.5 um) or Copper	Link length supported at the signaling rate in byte 140 or page 00h byte 222, for 62.5/125 um fiber (OM1), units of 1 m *, or copper cable attenuation in dB at 25.78 GHz.
		Cable Attenuation	
146	1	Length (passive copper or active cable or OM4 50 um)	Length of passive or active cable assembly (units of 1 m) or link length supported at the signaling rate in byte 140 or page 00h byte 222, for OM4 50/125 um fiber (units of 2 m) as indicated by Byte 147. See 6.3.12.
147	1	Device technology	Device technology
148-163	16	Vendor name	Free side device vendor name (ASCII)
164	1	Extended Module	Extended Module codes for InfiniBand.

165-167	3	Vendor OUI	Free side device vendor IEEE company ID.
168-183	16	Vendor PN	Part number provided by free side device vendor(ASCII)
184-185	2	Vendor rev	Revision level for part number provided by the vendor(ASCII)
186-187	2	Wavelength or Copper Cable Attenuation	Nominal laser wavelength (wavelength=value/20 in nm) or copper cable attenuation in dB at 2.5 GHz (Byte 186) and 5.0 GHz (Byte 187)
188-189	2	Wavelength tolerance or Copper Cable Attenuation	The range of laser wavelength (+/- value) from nominal wavelength. (wavelength Tol. =value/200 in nm) or copper cable attenuation in dB at 7.0 GHz (Byte 188) and 12.9 GHz (Byte 189)
190	1	Max case temp	Maximum case temperature
191	1	CC_BASE	Check code for base ID fields (Bytes 128-190)
192	1	Link codes	Extended Specification Compliance Codes (See SFF-8024)
193-195	3	Options	Optional features implemented.
196-211	16	Vendor SN	Serial number provided by vendor.(ASCII)
212-219	8	Date Code	Vendor's manufacturing date code.
220	1	Diagnostic Monitoring Type	Indicates which type of diagnostic monitoring is implemented (if any) in the free side device. Bit 1,0 Reserved.
221	1	Enhanced Options	Indicates which optional enhanced features are implemented in the free side device.
222	1	CC_EXT	Check code for the Extended ID Fields (Bytes 192-222)
224-255	32	Vendor Specific	Vendor Specific EEPROM

SFP Monitoring Specification

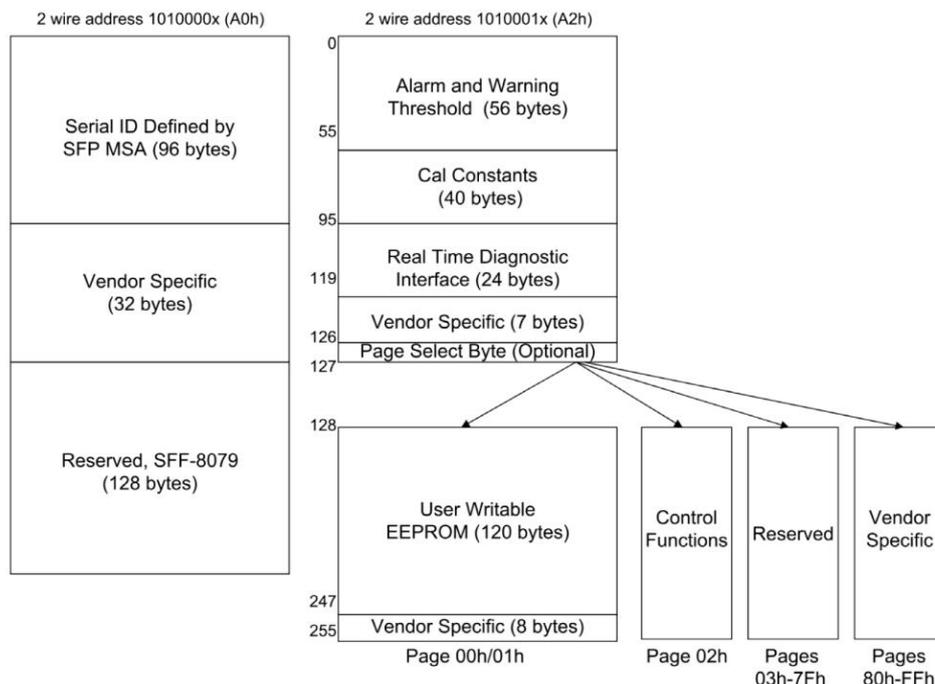


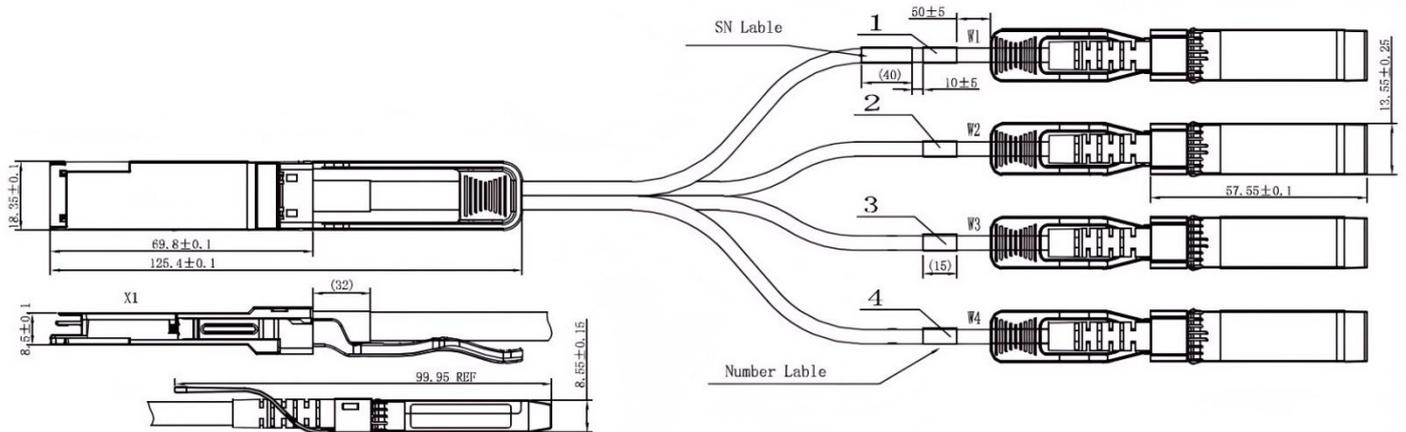
Figure6:SFP Memory map

SFP Memory map Table

Byte	Unit	Name	Description
A0h ID Fields			
0	1	Identifier	Type of transceiver
1	1	Ext. Identifier	Extended identifier of type of transceiver
2	1	Connector	Code for connector type
3-10	8	Transceiver	Code for electronic or optical compatibility
11	1	Encoding	Code for high speed serial encoding algorithm
12	1	Signaling Rate, Nominal	Nominal signaling rate, units of 100 MBd.
13	1	Rate Identifier	Type of rate select functionality
14	1	Length (SMF,km) or Copper Cable Attenuation	Link length supported for single-mode fiber, units of km, or copper cable attenuation in dB at 12.9 GHz
15	1	Length (SMF) or Copper Cable Attenuation	Link length supported for single-mode fiber, units of 100 m, or copper cable attenuation in dB at 25.78 GHz
16	1	Length (50 um, OM2)	Link length supported for 50 um OM2 fiber, units of 10 m
17	1	Length (62.5 um, OM1)	Link length supported for 62.5 um OM1 fiber, units of 10 m
18	1	Length (OM4 or copper cable)	Link length supported for 50um OM4 fiber, units of 10 m. Alternatively, copper or direct attach cable, units of m
19	1	Length (OM3) or Cable length, additional	Link length supported for 50 um OM3 fiber, units of 10 m. Alternatively, copper or direct attach cable multiplier and base value
20-35	16	Vendor name	SFP vendor name (ASCII)
36	1	Transceiver	Code for electronic or optical compatibility
37-39	3	Vendor OUI	SFP vendor IEEE company ID
40-55	16	Vendor PN	Part number provided by SFP vendor (ASCII)
56-59	4	Vendor rev	Revision level for part number provided by vendor (ASCII)
60-61	2	Wavelength	Laser wavelength (Passive/Active Cable Specification Compliance)
62	1	Fibre Channel Speed 2	Transceiver's Fibre Channel speed capabilities
63	1	CC_BASE	Check code for Base ID Fields (addresses 0 to 62)
64-65	2	Options	Indicates which optional transceiver signals are implemented
66	1	Signaling Rate, max	Upper signaling rate margin, units of %
67	1	Signaling Rate, min	Lower signaling rate margin, units of %
68-83	16	Vendor SN	Serial number provided by vendor (ASCII)
84-91	8	Date code	Vendor's manufacturing date code

92	1	Diagnostic Monitoring Type	Indicates which type of diagnostic monitoring is implemented (if any) in the transceiver
93	1	Enhanced Options	Indicates which optional enhanced features are implemented (if any) in the transceiver
94	1	SFF-8472 Compliance	Indicates which revision of SFF-8472 the transceiver complies with.
95	1	CC_EXT	Check code for the Extended ID Fields (addresses 64 to 94)
96-127	32	Vendor Specific	Vendor Specific EEPROM
128-255	128	Reserved	Reserved (was assigned to SFF-8079)

Mechanical Dimension



Note:

- Unit: mm
- Tolerance: $\varnothing 0.1$ mm if not shown
- Latch color: black
- When $L \leq 2$ m, the tolerance is ± 25 mm, when $L > 2$ m, the tolerance is $\pm 1\%$

Waring:

- The transceiver optics is supplied with a dust cover. This plug protects the transceiver optics during standard manufacturing processes by preventing contamination from air borne particles. It is recommended that the dust cover remain in the transceiver whenever an optical fiber connector is not inserted.
- Handling Precautions: This device is susceptible to damage as a result of electrostatic discharge (ESD). A static free environment is highly recommended. Follow guidelines according to proper ESD procedures.
- Laser Safety: Radiation emitted by laser devices can be dangerous to human eyes. Avoid eye exposure to direct or indirect radiation.